



BGA/CSP DEVELOPMENT UPDATE SERVICE

First Quarter, 2003

The first quarterly BGA/CSP Update for 2003 features special coverage of mobile phone production and market trends in China. Photos and an analysis of the components used in two domestic Chinese mobile phones are included. Major trends in RF packaging are described, including new package developments from Amkor, Carsem, Fujitsu, RF Micro Devices, Skyworks, and Tessera. A detailed analysis of the world's production capacity for tape/flex circuit used in IC packages is provided along with descriptions of the current technology from each tape/flex circuit maker. Worldwide capacity is provided for single-metal and two-metal layer tape. New package developments are described, including an embedded wafer level package developed jointly by CMK and Casio Micronics, and UTAC's stacked package. Integrated passive substrate developments from Mitsubishi Electric and Shinko Electric are also described.

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Contents and specifications subject to change without notice. 06/12/03